

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-10 (Canceled)

Claim 11 (Currently Amended)

A substrate treating apparatus for performing a predetermined treatment of substrates, comprising:

- a treating tank for immersing the substrates in a treating liquid stored therein;
- a holding arm for holding the substrates in vertical posture, said holding arm being movable to a treating position in said treating tank for immersing the substrates in the treating liquid;

- a storage device which stores a relationship between use history and treating rate of the treating liquid and an up-to-date use history of the treating liquid;

- a calculating device which derives a current treating rate R_m from said relationship between use history and treating rate of the treating liquid and said up-to-date use history of the treating liquid; and

- a computing device which ~~determines~~ derives a corrected treating time ~~by extending a predetermined treating time according to said current treating rate~~ A₁ from;

$$A_1 = T_i \bullet (R_i / R_m)$$

where T_i is a treating time specified in a recipe with reference to a fresh portion of said treating liquid, and R_i is a treating rate of the fresh portion;

wherein said substrates are treated for said corrected treating time A₁.

Claim 12 (Previously Presented)

A apparatus as defined in claim 11, wherein said calculating device is arranged to take into account at least one of a treated number of substrates, a treating rate, a treating time, a substrate type, a rate of over-treatment, a substrate coverage of film and an initial treating rate.

Claim 13 (Previously Presented)

A apparatus as defined in claim 11, wherein said calculating device is arranged to take into account at least one of a treated number of substrates, a treating time and a substrate coverage of film.

Claim 14 (Currently Amended)

A apparatus as defined in claim 11, wherein said ~~calculating~~ treating time is an etching time and said treating rate is an etching rate, and said computing device is arranged to derive said corrected treating time from;

$$A1 = Ti \bullet (Ri/Rm)$$

where Ti is an etching time specified in a recipe with reference to a fresh portion of said treating liquid, Ri is an etching rate of the fresh portion, and Rm is the current etching rate.

Claims 15-16 (Canceled)**Claim 17 (Original)**

A apparatus as defined in claim 11, wherein said treating liquid includes phosphoric acid.

Claim 18 (Original)

A apparatus as defined in claim 12, wherein said treating liquid includes phosphoric acid.

Claim 19 (Original)

A apparatus as defined in claim 14, wherein said treating liquid includes phosphoric acid.